

AN13571

基于LPC553x/LPC55S3x的无刷直流电机控制演示

第4版—2024年1月30日

应用笔记

文档信息

信息	内容
关键词	LPC553x/LPC55S3x处理器、嵌入式系统、3相无刷直流电机控制、霍尔传感器、基于Arm Cortex-M33的微控制器
摘要	本应用笔记介绍了基于恩智浦LPC553x/LPC55S3x处理器的带霍尔传感器的三相无刷直流电机控制实现方案。



1 介绍

本应用笔记介绍了基于恩智浦LPC553x/LPC55S3x处理器的带霍尔传感器的三相无刷直流电机控制实现方案。

LPC553x/LPC55S3x是一款基于Arm Cortex-M33的面向嵌入式应用的微控制器，它们包含了：

- 高达256kB的片上闪存
- 高达128kB的片上SRAM
- 1个SCTimer/PWM
- 8个灵活型串行通信外设，可配置为USART、SPI、高速SPI、I2C或I2S接口
- 2个16位采样率为每秒200万次的ADC（12位模式下的采样率为每秒330万次），能够同时进行4个转换
- 4个比较器
- 2个温度传感器
- 3个12位采样率为每秒100万次的DAC
- 3个运算放大器
- 2个FlexPWM定时器

Arm Cortex-M33提供了一个安全基础，采用TrustZone技术提供隔离，以保护宝贵的IP和数据。它通过集成的数字信号处理（DSP）指令简化了数字信号控制系统的设计和软件开发。

本应用笔记介绍了带霍尔传感器的无刷直流电机六步控制的原理、硬件和软件实现，包括详细的外设设置和驱动描述。

2 LPC553x/LPC55S3x的特性和优势

LPC553x/LPC55S3x是一款基于Arm Cortex-M33、面向嵌入式应用的微控制器。Arm Cortex-M33提供了一个安全基础，采用TrustZone技术提供隔离，以保护宝贵的IP和数据。它通过集成的数字信号处理（DSP）指令简化了数字信号控制系统的设计和软件开发。为了满足安全需求，LPC553x/LPC55S3x支持多种安全功能，如安全启动、高级加密标准（AES）、Rivest-Shamir-Adleman（RSA）、通用唯一标识符（UUID）、设备标识符组合引擎（DICE）、动态加解密、调试身份验证以及TBSA合规性。[图1](#)展示了这些特性。

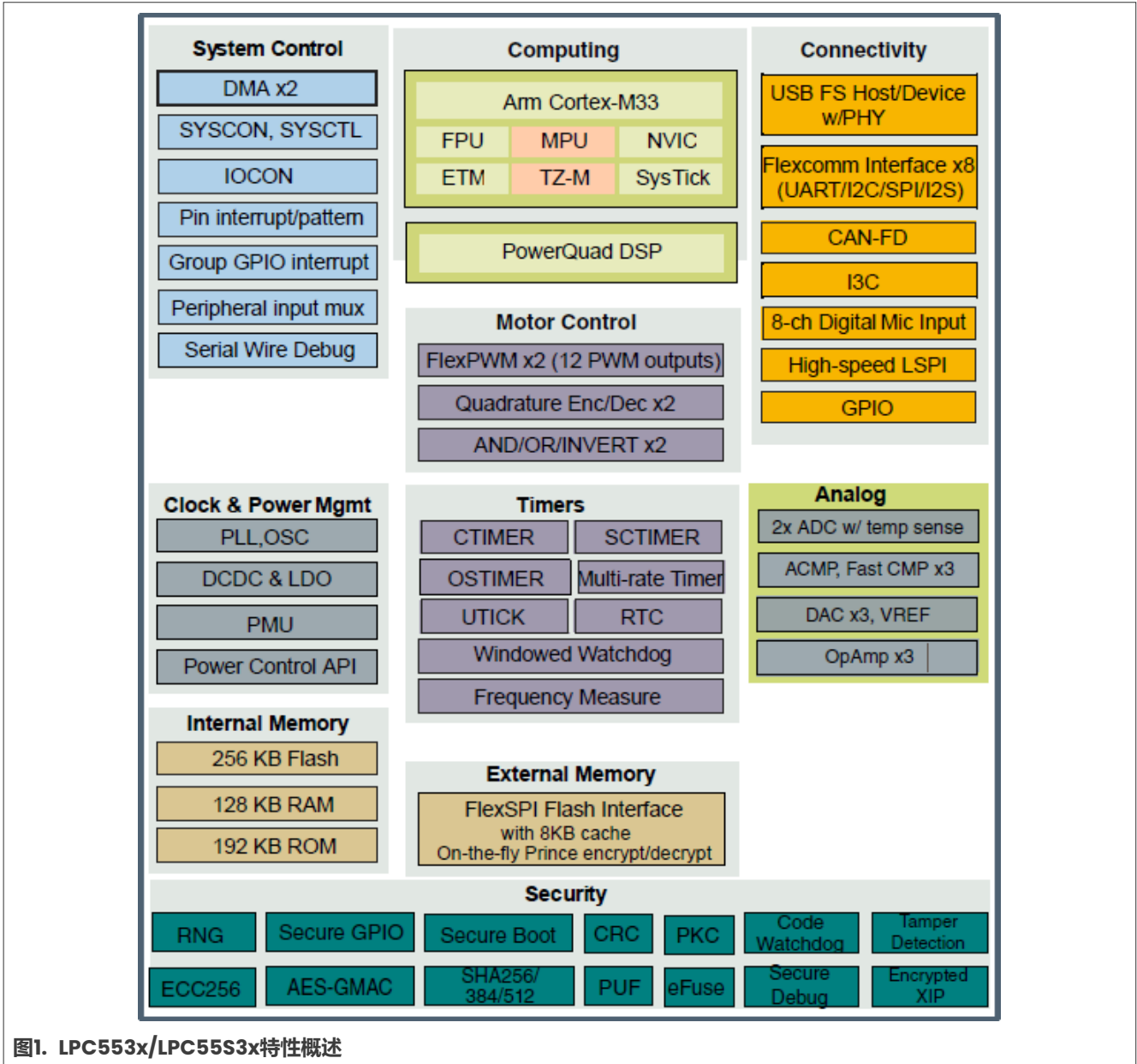


图1. LPC553x/LPC55S3x特性概述

对于无刷直流电机控制，LPC553x/LPC55S3x的优势如下：

- 多通道PWM信号输出。
- 丰富的定时器和通讯接口。
- 集成了丰富的内部模拟外设。

3 无刷直流电机控制理论

无刷直流电机是一种旋转式电动机械。它的定子与传统感应电机的三相定子类似，而转子表面贴装了永磁体。转子上没有碳刷，而是在特定的转子位置通过电子方式进行换向。图2所示为无刷直流电机的典型横截面。

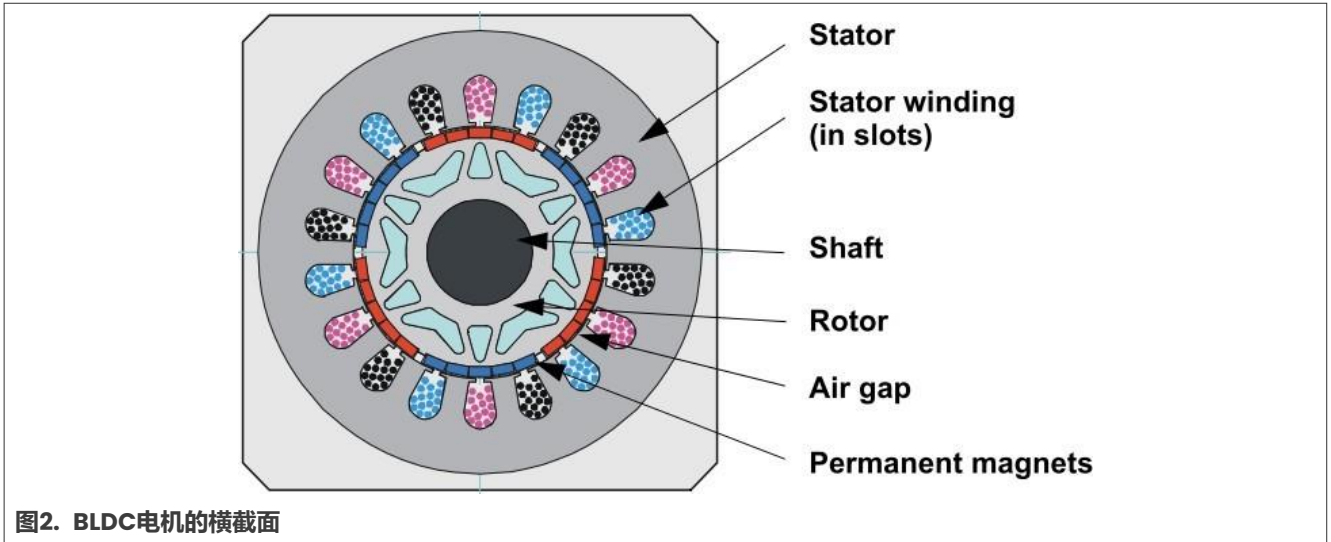


图2. BLDC电机的横截面

霍尔传感器安装在定子三相绕组的轴上，用于检测转子位置。

- 当转子磁体的直轴位置在某相位轴正方向的180°范围内时，对应相位反馈的霍尔传感器会得到高电平。
- 当转子磁体的直轴位置在预留的180°范围内时，对应相位反馈的霍尔传感器会得到低电平。

梯形反电动势的中点是转子的直轴与定子的相轴垂直的位置，在这个位置，霍尔传感器的输出信号会发生跳变，如图3所示。

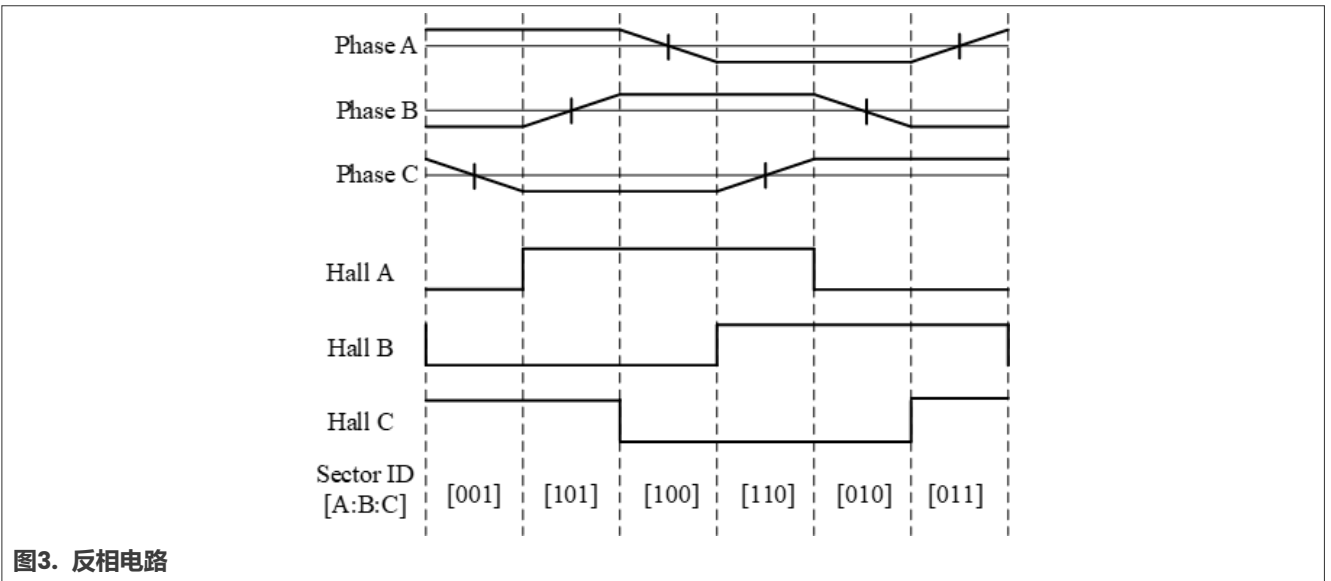
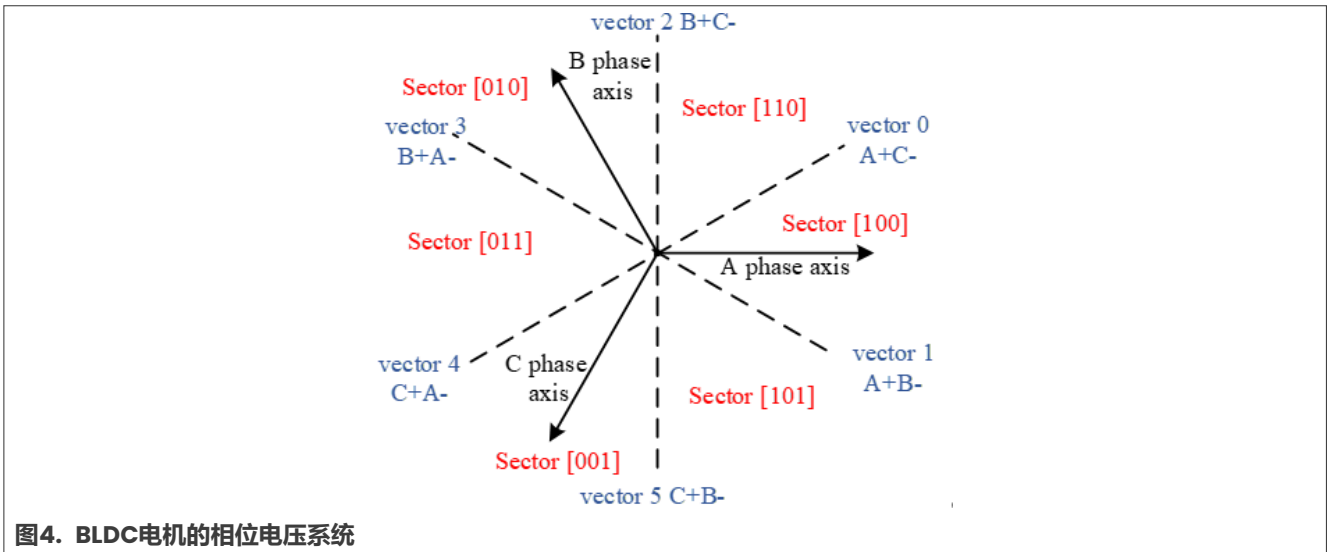


图3. 反相电路

三相霍尔传感器不会同时输出全0或全1的信号，因此转子的电角度可以划分为6个60°的扇区。在方波控制方法中，只选择三相绕组中的两个同时导通，并且产生的电压矢量与霍尔传感器划分的扇区的边界重合。扇区与电压矢量的位置关系如图4所示。



根据扇区的位置和所需的电机旋转方向，选择适当的电压矢量和方波占空比。例如，当转子的直轴在扇区[100]时，如果电机逆时针旋转，则选择电压矢量2，如果电机顺时针旋转，那么选择电压矢量5。

根据不同的应用场景，可以使用双斩波PWM调制和单斩波调制，如H_PWM-L_ON、H_ON-L_PWM、PWM-ON和ON-PWM。

本例中使用的是双斩波PWM调制。

4 硬件和软件实现

本章介绍了硬件和软件的实现。

4.1 系统硬件设计

应用硬件包括以下部分：

- LPCXpresso55S36-EVK

LPCXpresso55S36-EVK板设计为在独立模式下工作，或作为LPC553x/LPC553x的主板工作。板载接口包括RGB和其他LED接口。两个电机控制接口用于无刷直流电机控制应用。每个接口包括三相PWM输出和相应的采样信号输入接口。

- FRDM-MC-LVBLDC

FRDM-MC-LVBLDC低压三相无刷直流电机Freedom开发板平台为您的设计应用增加了无刷直流电机控制功能，如旋转或线性运动。

选用了LINIX 45ZVN24-40无刷直流电机。电机控制开发平台结构框图和实际演示图片如图5和图6所示。

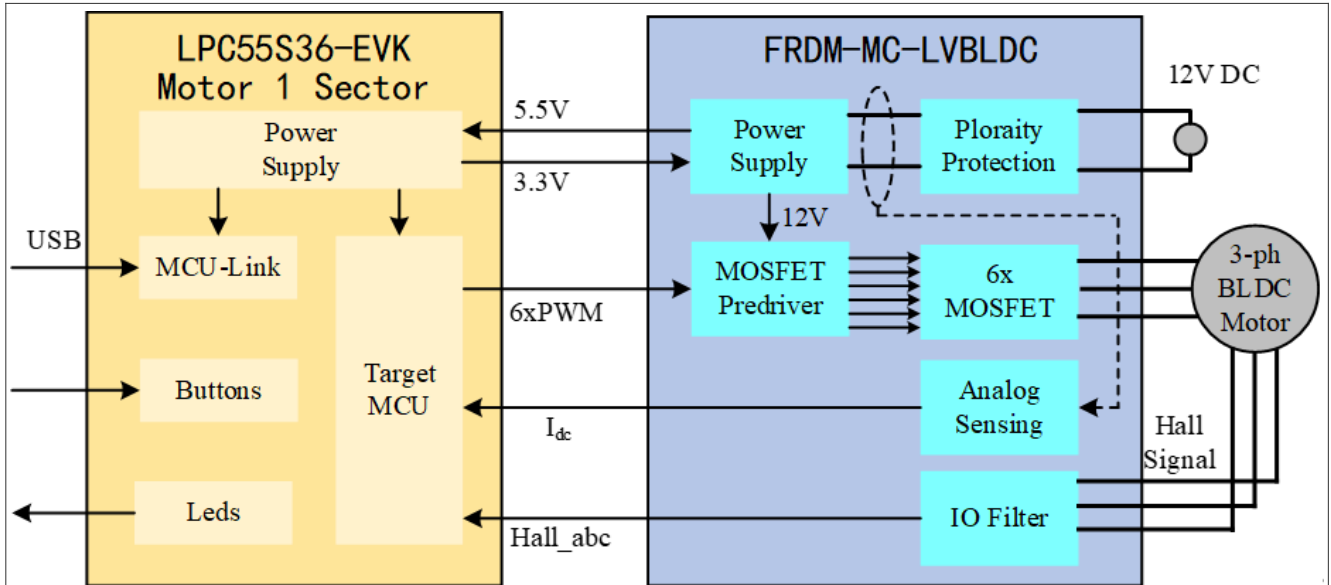


图5. 电机控制开发平台结构框图



图6. 实际演示图片

4.2 系统软件设计

软件和硬件应用可以满足以下设计要求：

- 选择LPC553x/LPC55S3x作为控制器
- 基于霍尔传感器的速度闭环控制
- 基于硬件和软件的过压、欠压和过流故障保护
- 最低转速为300转/分，最高转速为2200转/分
- 默认限制电流设置为4A
- 支持两个旋转方向
- 可以从任何电机位置启动，无需转子对准

图7所示为系统结构框图。整个控制流程包括三个部分。

- 通讯

霍尔信号的采集和换向控制是在PINT产生的通讯中断中完成的。要选择转子所在的扇区，在此中断中轮询连接到霍尔信号的GPIO值。同时，定时器存储换向时间。

- 定时控制环路

速度PI控制器计算、应用状态机更新和软件故障保护在由PWM慢环触发的ADC ISR (1kHz) 中完成。在定时控制环路中更新速度PI控制器的输出PWM占空比。读取缓存换向时间来计算速度。

- 软硬件保护

HSCMP实现了母线电流的硬件保护。它向eFlexPWM和DAC生成故障信号，可以用来配置电流保护阈值。软件保护在控制环路中执行。

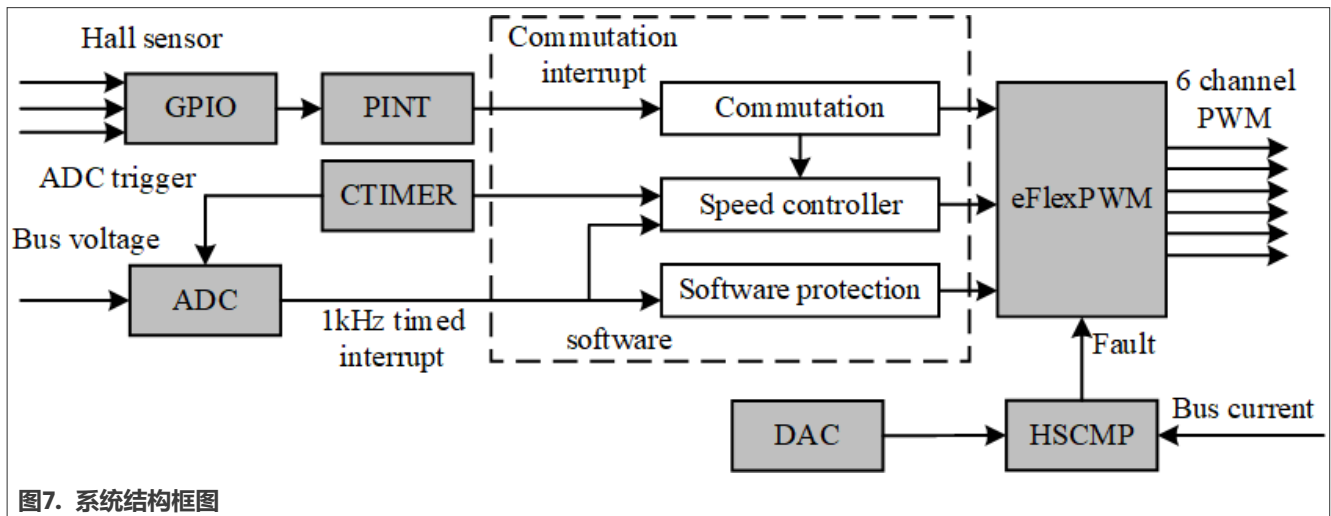


图7. 系统结构框图

5 外设置置

本节介绍LPC553x/LPC553x上用于电机控制的外设的配置，包括eFlexPWM、CTIMER、ADC、PINT、GINT、DAC和HSCMP。

5.1 eFlexPWM

配置eFlexPWM0生成6个PWM输出来驱动无刷直流电机，并使能子模块0的计数重置，使子模块1和2同步。

eFlexPWM0的配置包括：

- 启用IPBus时钟源150MHz。
- 全周期重新加载和全周期重新启用

子模块0

- 运行频率为20kHz，周期为5 μ s。
- 输出边缘对齐且高电平为真的互补PWM，死区时间为1 μ s。
- 从该子模块生成的PWM重新加载和初始化信号送到子模块1、2。

子模块1、子模块2

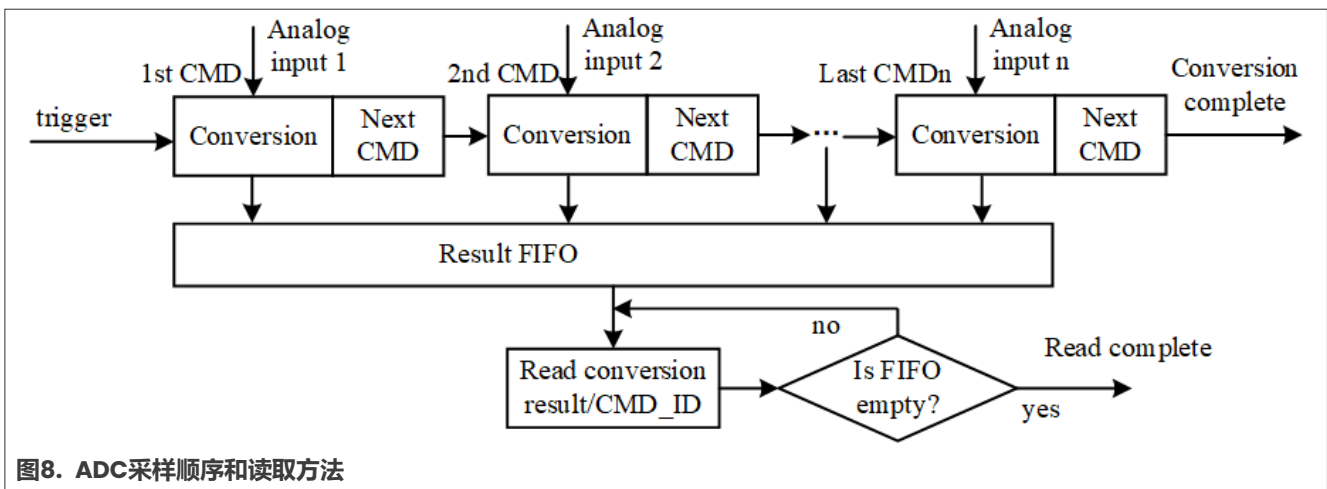
- 运行频率为20kHz，周期为5 μ s。
- 输出边缘对齐且高电平为真的互补PWM，死区时间为1 μ s。
- PWM重新加载和初始化信号来自子模块0。

5.2 ADC

ADC对直流母线电压进行采样。其采样值用于与用户给出的过压值和欠压值进行比较。ADC实现了对电机控制系统的软件保护。

ADC配置包括：

- 总线时钟源。时钟分频值为2。
- 标准分辨率。单端12位转换。
- 要对直流母线电压进行采样，请配置采样通道P0_10/ADC0_1A通道。



5.3 CTIMER

CTIMER0用于：

- 生成1kHz触发器以触发ADC转换
- 进入定时控制中断以执行速度控制

CTIMER0的配置包括：

- 固定频率时钟源FRO 96MHz。
- 在定时器模式下工作，在匹配值3时复位。
- 通过INPUTMUX将MAT3连接到ADC TRIG0。

CTIMER1自由运行，记录并缓存每个扇区的换向时间点，用于速度计算。CTIMER1的配置包括：

- 固定频率时钟源FRO 96MHz。

5.4 GPIO

表1列出了EVK板上与BLDC控制有关的GPIO配置。

表1. GPIO配置

引脚号	引脚名称	引脚功能	引脚号	引脚名称	引脚功能
11	PIO1_20	PWM0_A0	70	PIO0_13	GPIO_input
91	PIO1_17	PWM0_B0	71	PIO0_14	GPIO_input
50	PIO1_6	PWM0_A1	78	PIO1_11	GPIO_input
40	PIO1_22	PWM0_B1	30	PIO1_19	ADC0_1A
36	PIO1_8	PWM0_A2	35	PIO1_5	HSCMP0_IN3

表1. GPIO配置 (续)

引脚号	引脚名称	引脚功能	引脚号	引脚名称	引脚功能
75	PIO1_4	PWM0_B2			

GPIO配置可以通过MCUXpresso IDE的配置工具来实现，如图9所示。

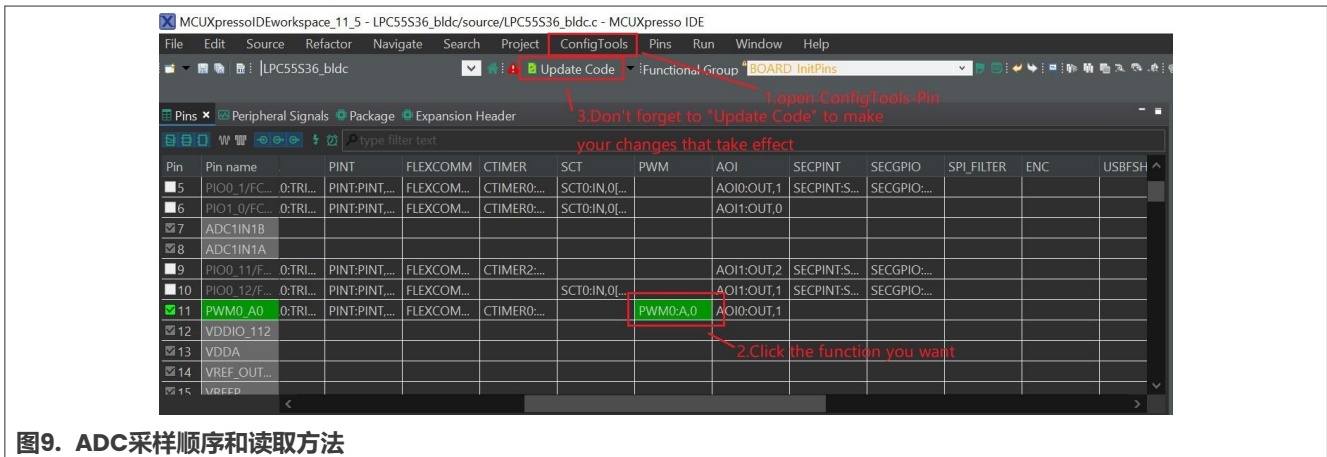


图9. ADC采样顺序和读取方法

5.5 GINT

GINT0用于生成通用中断，以检测SW3开关状态，由用户实现控制功能。GINT0的配置包括：

- 启用AHB时钟。
- 电平触发和低电平有效。
- 启用PIO1_17参与分组中断。

5.6 PINT

PIN_INT_IRQ 0-2用于分别检测霍尔信号A、B和C的边沿，以产生中断并完成通讯。PINT0的配置包括：

- 分别选择PIO0_13、PIO0_14和PIO1_11作为PIN_INT_IRQ 0-2的中断源。
- 电平触发，上升和下降沿均处于活动状态。

5.7 DAC

DAC用于配置母线电流阈值和HSCMP的负输入。DAC0的配置包括：

- 启用时钟源的主时钟150MHz，除以6，得到25MHz时钟。
- 选择VREFHI作为参考电压。
- 使用OPAMP作为DAC模拟缓冲器。
- DAC转换值为 $DATA \times 3.3V / 4096$ 。

5.8 HSCMP

HSCMP用于比较母线电流采样信号与用户配置的DAC阈值，以执行硬件保护。HSCMP0的配置包括：

- 输入“-” = 外部DAC，输入“+” = 模拟多路复用器的第三输入，高功率/高速模式。
- 将比较输出连接到eFlexPWM的故障。

6 软件实现

本节介绍无刷直流电机应用的软件设计。

6.1 状态机

在ADC中断中实现了一个状态机控制，用于控制电机的运行状态，如图10所示。

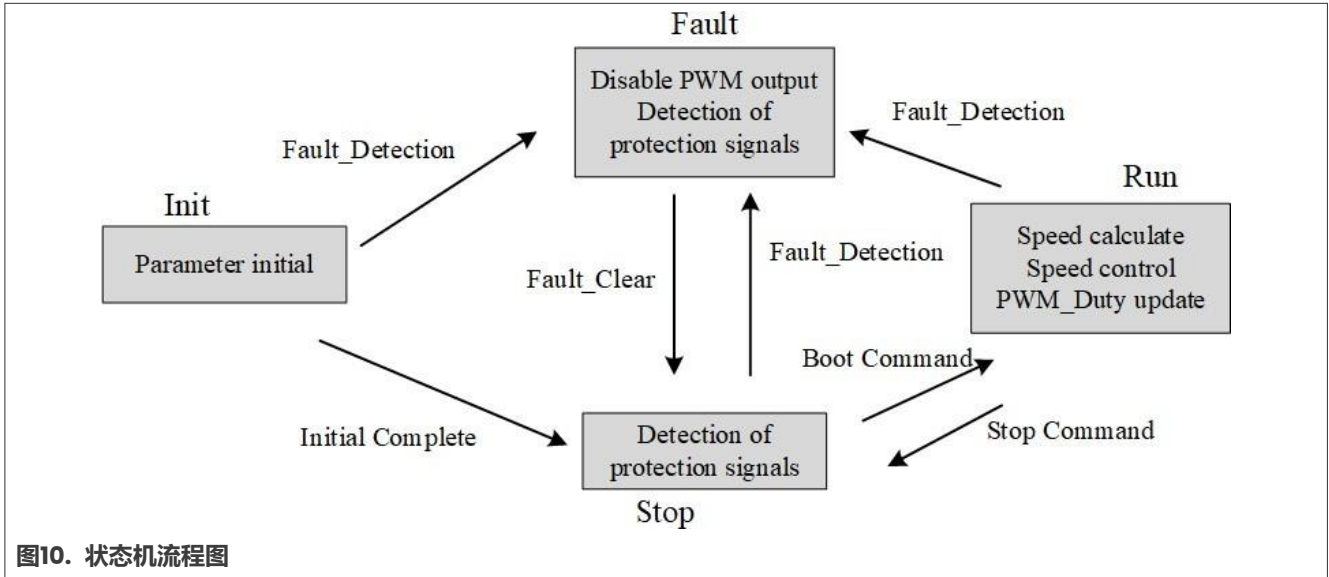


图10. 状态机流程图

6.2 转速计算

CTIMER1记录每个扇区的持续时间。电机转速（RPM）可以根据前6个扇区的时间来计算。

$$Speed_Fed = \frac{60}{Cnt_{SixSector} * Period * Polepair} \tag{1}$$

7 演示的操作

本章介绍该演示的操作。

7.1 电机参数

表2提供了电机规格。

表2. 电机规格

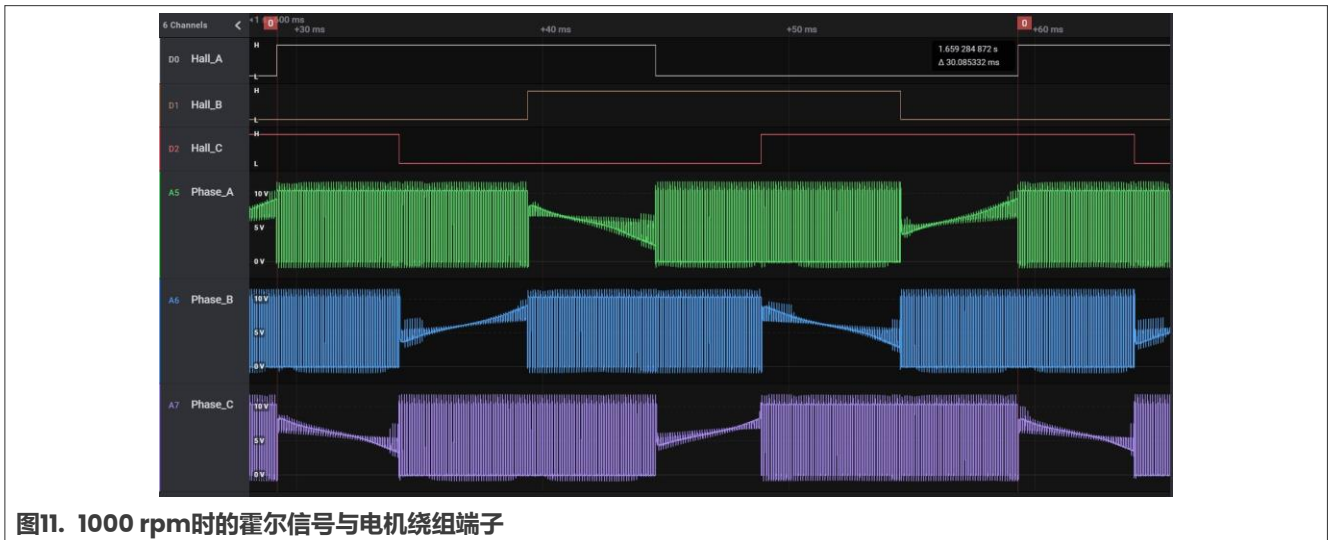
制造商名称	Linux	定子电阻/Ohm	1
型号	45ZWN24-40	定子绕组电感d轴/μH	426
额定转速/rpm	4000	定子绕组电感q轴/μH	460
额定线路电压/V	24	极对数	2
额定功率/W	40	反电动势常数/V.s.rad-1	0.01456

在设置电机的应用参数（如速度PI控制器和启动电流值）时，需要考虑到轴上安装了塑料环（作为套件的一部分）。如果没有考虑这个因素，电机的转速可能会出现波动。

7.2 演示的实验性能

如图11所示，当电机以1000rpm的速度运行时，

- 霍尔传感器的信号交替变化。
- 电机绕组端子的电压根据霍尔信号的输出被切割。
- 相反电位为零交叉波形，无导通。



7.3 CPU负载和内存使用情况

表3所示为演示程序的空间使用情况和内核负载。使用SYSTick定时器测量CPU负载。

表3. LPC553x/LPC55S3x无刷直流电机控制演示CPU负载和内存使用

代码存储器[字节]	20132
数据存储器[字节]	8720
CPU周期	257
CPU负载	1.71%

8 参考资料

这些参考资料可在www.nxp.com.cn上获得：

- 《LPC553x参考手册》（文档LPC553xRM）
- 《MCUXpresso SDK三相永磁同步电机控制（LPC）》（文档3PPMSMCLPCUG）

9 修订历史

表4汇总了对本文档的修订。

表4. 修订历史

版本号	发布日期	说明
4	2024年1月30日	更正了 第6节 中的一个拼写错误。
3	2023年12月7日	根据SDK、IDE和EVK板的更新进行了更新
2	2023年7月17日	<ul style="list-style-type: none">更新了第4.1节更新了第5.1节更新了第5.3节更新了第7.3节
1	2022年5月25日	将LPC55S3x替换为LPC553x/LPC55S3x
0	2022年3月25日	初版发布

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